

WHAT IS CLAIMED IS:

1. A method for making a printed circuit board having jumper lines, comprising the steps of:

a) making a printed circuit board;

b) coating or printing a dielectric material on the printed circuit board to form an isolation layer;

c) forming multiple pads in the isolation layer of the dielectric material, thereby exposing part of the printed circuit board without covered by the dielectric material; and

d) coating or printing a high conductive material on the isolation layer of the dielectric material to connect the multiple pads, thereby forming a planar jumper layer that is connected to the printed circuit board through the circular pads.

2. The method for making a printed circuit board having jumper lines in accordance with claim 1, wherein the dielectric material is a high dielectric value material.

3. The method for making a printed circuit board having jumper lines in accordance with claim 1, wherein the step a) further includes the steps of:

determining a pre-estimated value of an effective dielectric constant;

determining a shortened size of a microwave circuit according to the pre-estimated value of the effective dielectric constant and a used working frequency; and

making a printed circuit board containing the microwave circuit according to the shortened size that is determined.

4. A method for making a printed circuit board having jumper lines,
comprising the steps of:

a) determining a pre-estimated value of an effective dielectric
constant;

b) determining a shortened size of a microwave circuit according to
the pre-estimated value of the effective dielectric constant and a used working
frequency;

c) providing a dielectric substrate that may increase the effective
dielectric constant to the pre-estimated value;

d) making the microwave circuit with a shortened size on the
dielectric substrate;

e) coating or printing an isolation layer on the microwave circuit;

f) forming multiple pads in the isolation layer, thereby exposing part
of the microwave circuit without covered by the isolation layer; and

g) coating or printing a high conductive material on the isolation
layer to connect the multiple pads, thereby forming a planar jumper layer that
is connected to the microwave circuit through the circular pads.

5. A printed circuit board having jumper lines, comprising: a line
layer, an isolation layer made of a dielectric material coated on the line layer,
multiple pads formed in the isolation layer, thereby exposing part of the line
layer without covered by the isolation layer, and a high conductive material
coated on the isolation layer to connect the multiple pads, thereby forming a
planar jumper layer that is connected to the line layer through the circular pads.

1 6. The printed circuit board having jumper lines in accordance with
2 claim 5, wherein the printed circuit board may be overlapped with other circuit
3 substrates, thereby forming a multi-layer printed circuit board.

4 7 A printed circuit board having jumper lines, comprising: a
5 dielectric substrate, a metallic ground layer mounted on a first side of the
6 dielectric substrate, and a line layer mounted on a second side of the dielectric
7 substrate, an isolation layer made of a high dielectric value material coated on
8 the line layer, multiple pads formed in the isolation layer, thereby exposing
9 part of the line layer without covered by the isolation layer, and a high
10 conductive material coated on the isolation layer to connect the multiple pads,
11 thereby forming a planar jumper layer that is connected to the line layer
12 through the circular pads.

13 8. The printed circuit board having jumper lines in accordance with
14 claim 7, wherein the printed circuit board may be overlapped with other circuit
15 substrates, thereby forming a multi-layer printed circuit board.

16 9. A printed circuit board having jumper lines, comprising: a
17 dielectric substrate, a metallic ground layer mounted on one side of the
18 dielectric substrate, an isolation layer made of a high dielectric value material
19 coated on the metallic ground layer, multiple pads formed in the isolation layer,
20 thereby exposing part of the metallic ground layer without covered by the
21 isolation layer, and a high conductive material coated on the isolation layer to
22 connect the multiple pads, thereby forming a planar jumper layer that is
23 connected to the metallic ground layer through the circular pads.

10. The printed circuit board having jumper lines in accordance with claim 9, wherein the printed circuit board may be overlapped with other circuit substrates, thereby forming a multi-layer printed circuit board.

11. A printed circuit board having jumper lines, comprising: a dielectric substrate made of a high dielectric value material, a metallic ground layer mounted on a first side of the dielectric substrate, a line layer mounted on a second side of the dielectric substrate, an isolation layer coated on the line layer, multiple pads formed in the isolation layer, thereby exposing part of the line layer without covered by the isolation layer, and a high conductive material coated on the isolation layer to connect the multiple pads, thereby forming a planar jumper layer that is connected to the line layer through the circular pads.

12. The printed circuit board having jumper lines in accordance with claim 11, wherein the printed circuit board may be overlapped with other circuit substrates, thereby forming a multi-layer printed circuit board.

13. A printed circuit board having jumper lines, comprising: a dielectric substrate made of a high dielectric value material, a metallic ground layer mounted on one side of the dielectric substrate, an isolation layer coated on the metallic ground layer, multiple pads formed in the isolation layer, thereby exposing part of the metallic ground layer without covered by the isolation layer, and a high conductive material coated on the isolation layer to connect the multiple pads, thereby forming a planar jumper layer that is connected to the metallic ground layer through the circular pads.

1 14. The printed circuit board having jumper lines in accordance with
2 claim 13, wherein the printed circuit board may be overlapped with other
3 circuit substrates, thereby forming a multi-layer printed circuit board.
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